TEXAS INSTRUMENTS

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250626000.1
Qualification of LFAB as an additional Wafer Fab site option for select F65 devices
Change Notification / Sample Request

Date: June 26, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,
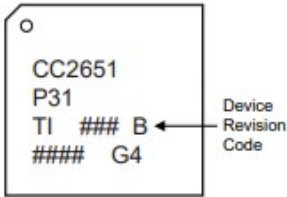
Change Management Team
SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC1311R31T0RGZR	NULL
CC1311P31T0RGZR	NULL
CC1311R31T0RKPR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250626000	PCN Date:	June 26, 2025
Title:	Qualification of LFAB as an additional Wafer Fab site option for select F65 devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	September 24, 2025	Sample requests accepted until:	August 25, 2025*

*Sample requests received after August 25, 2025 will not be supported.

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of LFAB as a Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
UMC12i / DMOS6	F65	300mm	LFAB	F65	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC12i	UMI	SGP	Singapore
DMOS6	DM6	USA	Dallas
LFAB	**LHI**	**USA**	**Lehi**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
B	**C**

Device Revision Code will change from B to C with the new wafer fab:

Debug registers that identify the device are also incremented.

Product Affected:

CC1311P31T0RGZR	CC1311R31T0RKPR	CC2651P31T0RKPR	CC2651R31T0RGZR
CC1311P31T0RGZR.A	CC1311R31T0RKPR.A	CC2651P31T0RKPR.A	CC2651R31T0RGZR.A
CC1311P31T0RGZR.B	CC1311R31T0RKPR.B	CC2651P31T0RKPR.B	CC2651R31T0RGZR.B
CC1311R31T0RGZR	CC2651P31T0RGZR	CC2651P31T0RKPRG4	CC2651R31T0RKPR
CC1311R31T0RGZR.A	CC2651P31T0RGZR.A	CC2651P31T0RKPRG4.A	CC2651R31T0RKPR.A
CC1311R31T0RGZR.B	CC2651P31T0RGZR.B	CC2651P31T0RKPRG4.B	CC2651R31T0RKPR.B

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1311R31T0RGZR	Qual Device: CC2651P31T0RGZR	Qual Device: CC2651R31T0RGZR	QBS Reference: CC2642R1FRGZR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0
HTOL	B1	Life Test*	125C	1000 Hours	-	-	-	3/231/0
EDR	B3	NVM Data Retention*	150C	1000 Hours	-	-	-	3/231/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/10/0	1/10/0	1/10/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device CC1311R31T0RGZR is qualified at MSL3 260C
- Qual Device CC2651P31T0RGZR is qualified at MSL3 260C
- Qual Device CC2651R31T0RGZR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2208-050

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.